

RD Number: RD200

RD Title: TC78H660FTG Evaluation Circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	CN1	1	CN-2P	—	—	PCB terminal block 2 positions		
2	CN2	1	CN-2P	—	—	PCB terminal block 2 positions		
3	CN3	1	CN-2P	—	—	PCB terminal block 2 positions		
4	CVM1	1	47μF 25V	—	—	Electrolytic Capacitor		
5	CVM2	1	0.1μF	—	—	Chip capacitor		
6	CEN	0	Not mount	—	—	Chip capacitor		✓
7	CVCC	1	0.1μF	—	—	Chip capacitor		
8	CVREF	1	0.1μF	—	—	Chip capacitor		
9	R1	0	Not mount	—	—	Chip resistor		✓
10	R2	0	Not mount	—	—	Chip resistor		✓
11	R3	1	10kΩ	—	—	Chip resistor		
12	R4	1	10kΩ	—	—	Chip resistor		
13	R5	1	10kΩ	—	—	Chip resistor		
14	R6	1	10kΩ	—	—	Chip resistor		
15	R7	1	10kΩ	—	—	Chip resistor		
16	R8	1	10kΩ	—	—	Chip resistor		
17	R9	1	10kΩ	—	—	Chip resistor		
18	R10	1	10kΩ	—	—	Chip resistor		
19	R11	0	Not mount	—	—	Chip resistor		✓
20	R12	0	Not mount	—	—	Chip resistor		✓
21	R13	0	Not mount	—	—	Chip resistor		✓
22	R14	0	Not mount	—	—	Chip resistor		✓
23	REN	1	10kΩ	—	—	Chip resistor		
24	ROSC	1	47kΩ	—	—	Chip resistor		
25	VR1	0	Not mount	—	—	Variable Resistor		✓
26	U1	1	TC78H660FTG	TC78H660FTG	TOSHIBA	Motor driver IC	QFN16	
27	SW0	0	Not mount	—	—	Toggle switch		✓
28	SW1	0	Not mount	—	—	Toggle switch		✓
29	SW2	0	Not mount	—	—	Toggle switch		✓
30	SW3	0	Not mount	—	—	Toggle switch		✓
31	AGND	0	Not mount	—	—	Check terminal		✓
32	EN (MODE)	0	Not mount	—	—	Check terminal		✓
33	ERR	0	Not mount	—	—	Check terminal		✓
34	MODE0 (IN2A/Phase B)	0	Not mount	—	—	Check terminal		✓
35	MODE1 (IN1B/Enable A)	0	Not mount	—	—	Check terminal		✓
36	MODE2 (IN1B/Enable B)	0	Not mount	—	—	Check terminal		✓

37	MODE3 (IN2B/Enable B)	0	Not mount	—	—	Check terminal		✓
38	OSCM	0	Not mount	—	—	Check terminal		✓
39	OUT_A+	0	Not mount	—	—	Check terminal		✓
40	OUT_A-	0	Not mount	—	—	Check terminal		✓
41	OUT_B+	0	Not mount	—	—	Check terminal		✓
42	OUT_B-	0	Not mount	—	—	Check terminal		✓
43	PGNDA	0	Not mount	—	—	Check terminal		✓
44	PGNDB	0	Not mount	—	—	Check terminal		✓
45	STBY	0	Not mount	—	—	Check terminal		✓
46	TP3	0	Not mount	—	—	Check terminal		✓
47	VM	0	Not mount	—	—	Check terminal		✓
48	VREF	0	Not mount	—	—	Check terminal		✓
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